



EMC Compo 2011

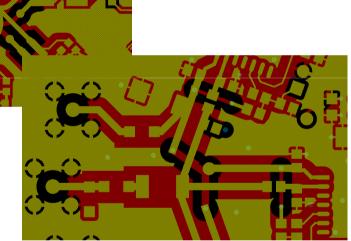
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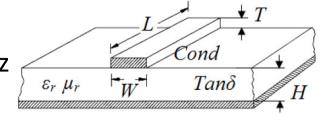
Full PCB circuit-electromagnetic simulations for high speed/RF applications

Industrial partner: On Semiconductor

Introduction

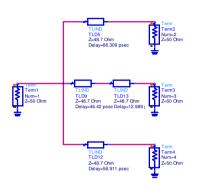
- Signal integrity and EMC are degraded in modern PCB designs because of the high operating frequencies and high density of the components present
 - Imperfect reference planes
 - Coupling
 - Bends and junctions
 - Transmission line width mismatch
 - Real passive components
- Transmission line theory assumptions are rarely satisfied on a real PCB
- Even if a PCB is designed for a lower frequencies, it still has to pass a test at 1 GHz

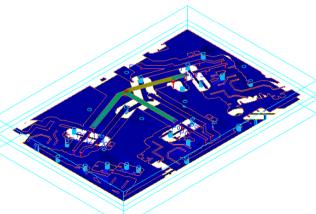




Objective

- Objective: full PCB simulations
 - Circuit simulators
 - Fast
 - But accurate only if the transmission line assumptions are valid
 - EM simulations
 - Mostly accurate
 - Slow
- Circuit vs EM simulators what to choose?
 - Both...
- Circuit-EM co-simulation
 - Can be reasonably fast and also reasonably accurate
 - Issues like what to choose for a simulation domain in EM simulator?

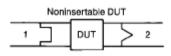




Current activities

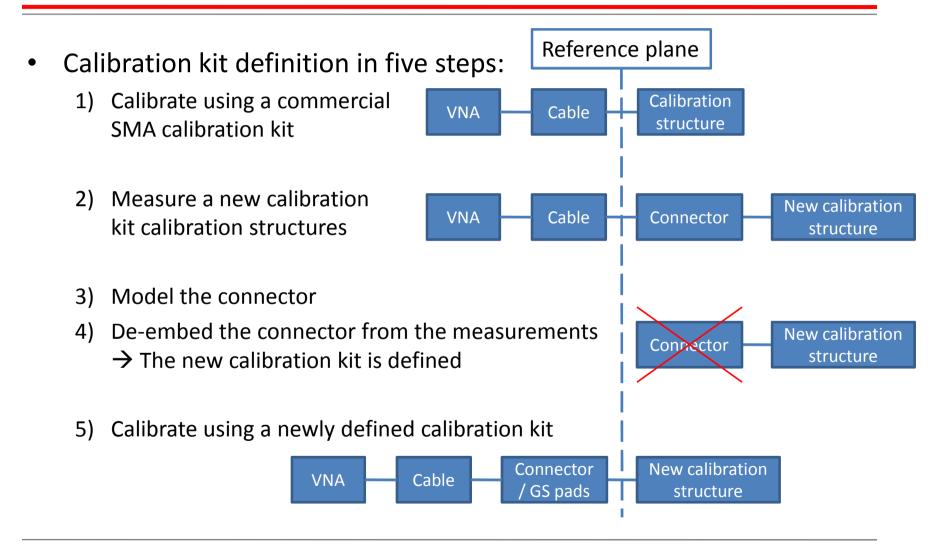
- Design of test cases for research, measuring and modelling
- Mixed-connector calibration
 - SMA coaxial connector on one port and ground-slot micro probe on the other port
 - Issue: how to define a thru?
 - Several techniques and methods exist: de-embedding, adapter removal, unknown thru
 - We have defined a calibration method for a
 - mixed-connector environment as a hybrid between the in situ calibration and de-embedding method



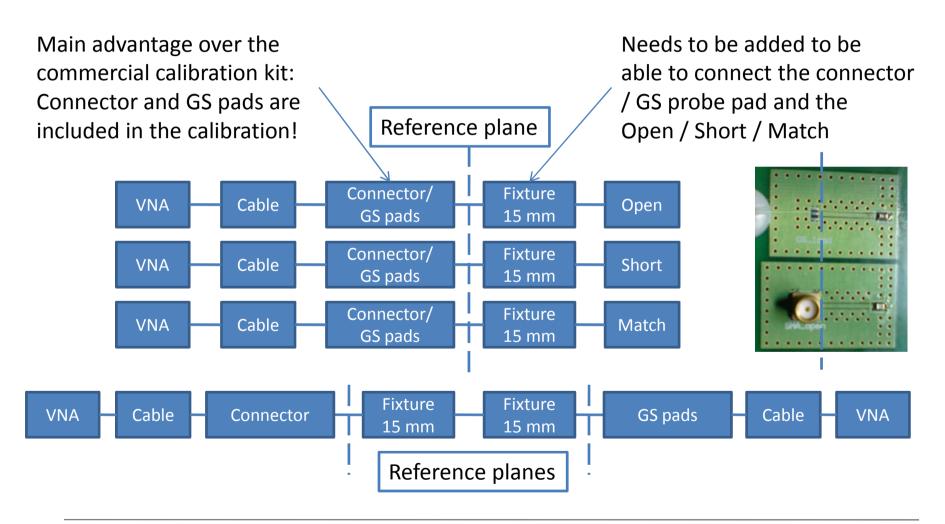




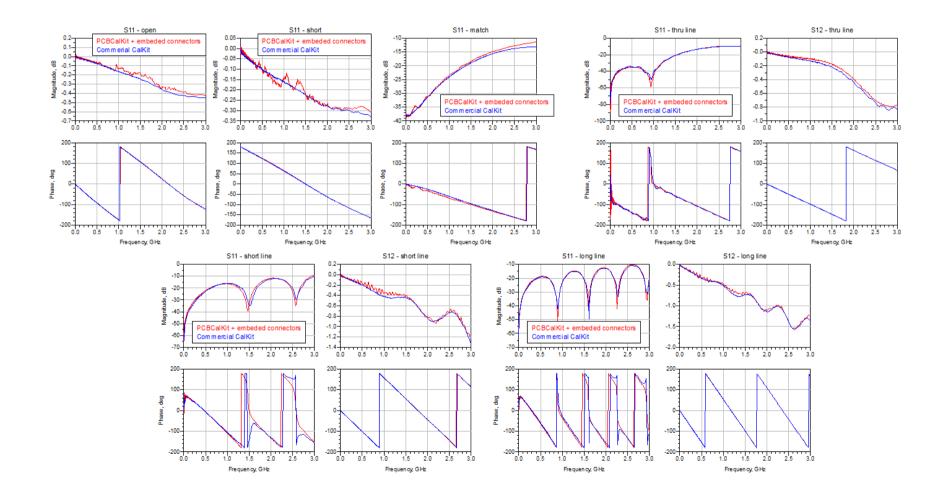
Calibration PCB



Calibration PCB

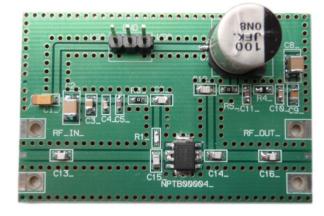


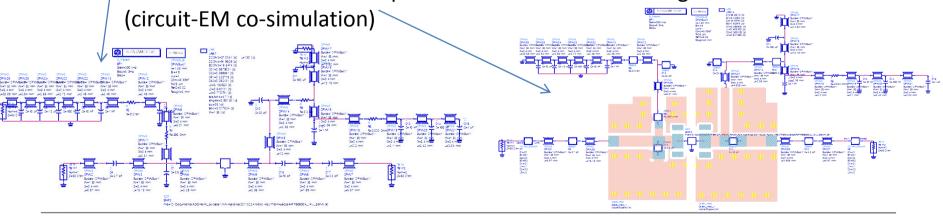
Results – Calibration PCB



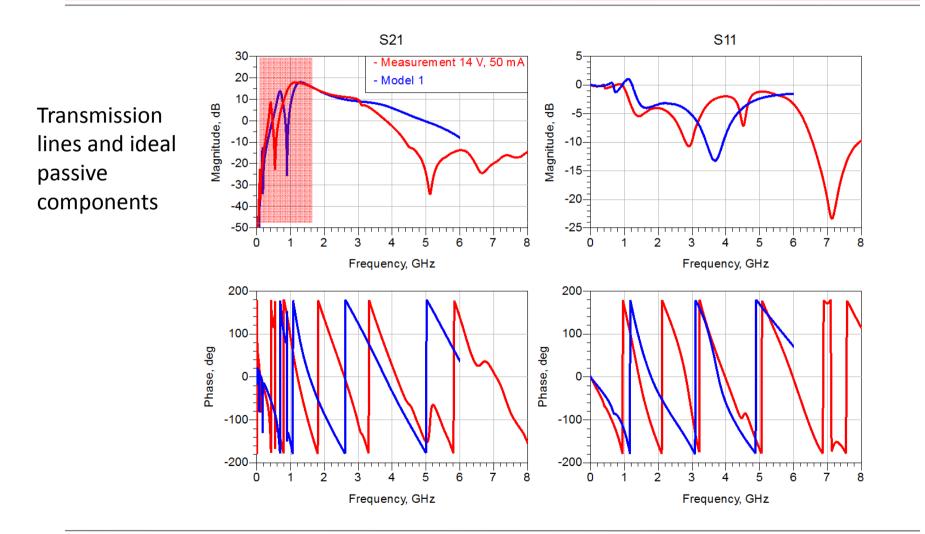
Amplifier test case

- A 2.5 GHz GaN HEMT amplifier has been ۲ simulated and compared to measurements to assess the accuracy of the simulations
- Simulations done: •
 - Model 1: transmission lines and ideal components
 - Model 2: Model 1 + real component models
 - Model 3: Model 2 + connector models
 - Model 4: Model 3 + critical parts simulated in electro-magnetic simulator (circuit-EM co-simulation)

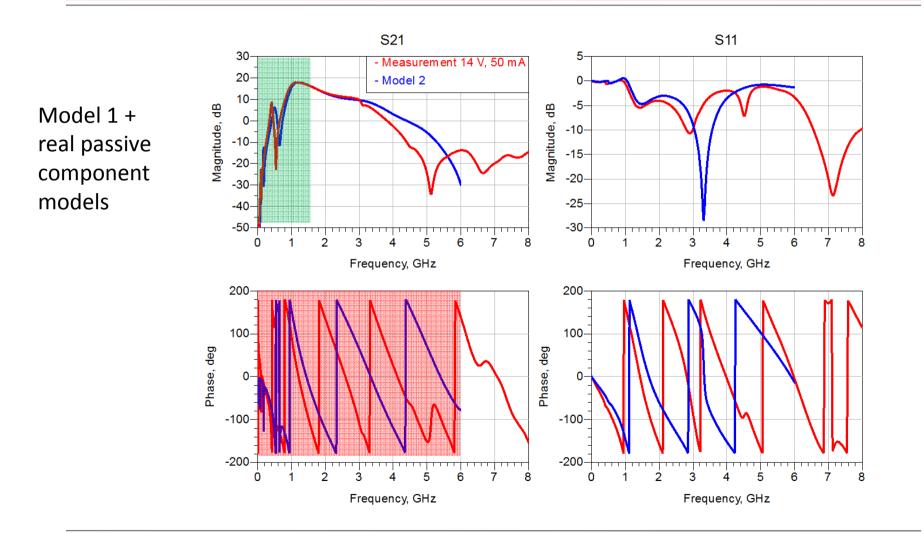




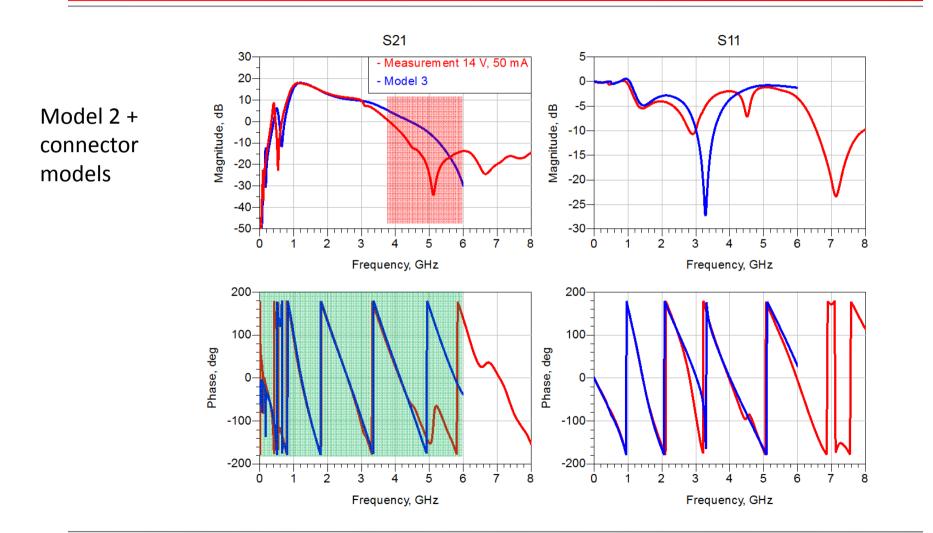
Results – model 1 vs measurements



Results – model 2 vs measurements

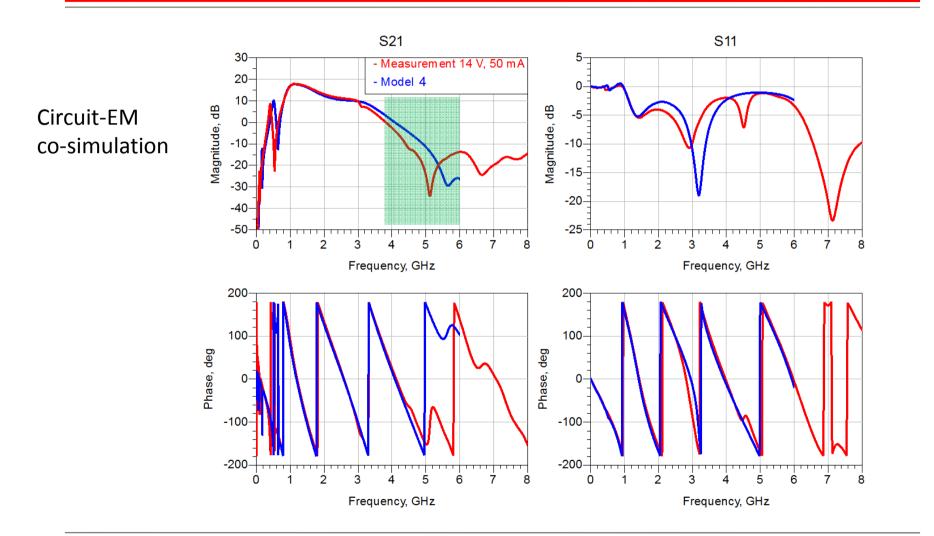


Results – model 3 vs measurements



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Results – model 4 vs measurements



Perspectives

- Still to do:
 - Measure several test cases on which we have been working on to validate the results of the circuit-EM co-simulation done so far
 - Compare the hybrid in situ / de-embedding calibration method with other mixed-connector calibrations
 - de-embedding method
 - unknown thru method
 - adapter removal method is not applicable for our test case
- The work shown here is a part of the project with On Semiconductor
 - Industrial environment
 - Real product PCB test cases
- A 1 year internship to KU Leuven is planned

Thank you for your attention...